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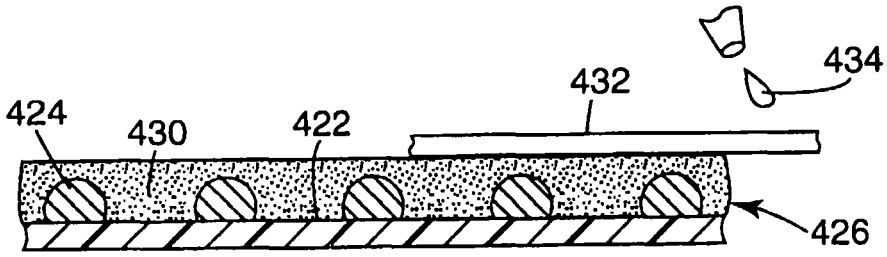
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(54) Title: SOLVENT ASSISTED BURNISHING OF PRE-UNDERFILLED SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDING



(57) Abstract: The present invention relates to a method for connecting an integrated circuit chip to a circuit substrate. The method includes the step of pre-applying adhesive directly to a bumped side of an integrated circuit chip. The method also includes the steps of removing portions of the adhesive from the tips of the solder bumps to expose a contact surface, and pressing the bumped side of the integrated circuit chip, which has previously been coated with adhesive, against the circuit substrate such that the bumps provide an electrical connection between the integrated circuit chip and the circuit substrate. The adhesive is removed from the tips of the solder bumps using a solvent assisted wiping action. The pre-applied adhesive on the chip forms a bond between the integrated circuit chip and the circuit substrate.

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